

WHAT IS CLAIMED IS:

1. A memory card, comprising:
 - a substrate having opposed top and bottom surfaces and a plurality of terminals disposed on the bottom surface thereof;
 - at least one component mounted to the top surface of the substrate and electrically connected to the terminals thereof;
 - a first encapsulation part formed on the bottom surface of the substrate; and
 - a second encapsulation part formed on the top surface of the substrate and encapsulating the component mounted thereto.
2. The memory card of Claim 1 wherein the first encapsulation part is formed to include an opening therein, the terminals of the substrate being exposed in the opening.
3. The memory card of Claim 1 wherein:
 - the second encapsulation part defines an opposed pair of sides; and
 - a pair of coupling notches are formed in respective ones of the sides of the second encapsulation part in opposed relation to each other.
4. The memory of Claim 1 wherein:
 - the terminals of the substrate extend in spaced, generally parallel relation to each other;
 - the second encapsulation part defines an opposed pair of peripheral edge segments which extend in spaced, generally parallel relation to the terminals; and
 - a pair of guide slots are formed in respective ones of the peripheral edge segments in opposed relation to each other.
5. The memory card of Claim 1 wherein the second encapsulation part includes a recess formed therein adjacent a peripheral edge segment of the second encapsulation part disposed furthest from the terminals.
6. The memory card of Claim 1 wherein the first encapsulation part and the second encapsulation part are each fabricated from an epoxy mold compound.
7. The memory card of Claim 1 wherein:
 - the first encapsulation part is of a first thickness; and
 - the second encapsulation part is of a second thickness which exceeds the first thickness.

8. The memory card of Claim 1 comprising multiple components mounted to the top surface of the substrate and electrically connected to the terminals thereof.

9. The memory card of Claim 8 wherein the components are selected from the group consisting of:

- a semiconductor package;
- a semiconductor die;
- a passive component; and
- combinations thereof.

10. The memory card of Claim 9 wherein:

the semiconductor package and the passive component are surface mounted to the top surface of the substrate; and

the semiconductor die is wire bonded to the substrate through the use of a conductive wire.

11. A method for fabricating a memory card, the method comprising the steps of :

- a) providing a substrate having opposed top and bottom surfaces and a plurality of terminals disposed on the bottom surface thereof;
- b) forming a first encapsulation part on the bottom surface of the substrate;
- c) mounting at least one component to the top surface of the substrate in a manner wherein the component is electrically connected to the terminals; and
- d) forming a second encapsulation part on the top surface of the substrate in a manner encapsulating the component mounted thereto.

12. The method of Claim 11 wherein step (b) comprises forming the first encapsulation part to include an opening therein, the terminals of the substrate being exposed in the opening.

13. The method of Claim 11 wherein step (d) comprises forming a pair of coupling notches into respective ones of an opposed pair of sides of the second encapsulation part in opposed relation to each other.

14. The method of Claim 11 wherein:

step (d) comprises forming a pair of guide slots into respective ones of an opposed pair of peripheral edge segments of the encapsulation part which extend in spaced, generally parallel relation to the terminals.

15. The method of Claim 11 wherein step (d) comprises forming a recess in the second encapsulation part along a peripheral edge segment thereof which is disposed furthest from the terminals.

16. The method of Claim 11 wherein steps (b) and (d) comprise forming the first and second encapsulation parts from an epoxy mold compound.

17. The method of Claim 11 wherein:

step (b) comprises forming the first encapsulation part to be of a first thickness;
and

step (d) comprises forming the second encapsulation part to be of a second thickness which exceeds the first thickness.

18. The method of Claim 11 wherein step (c) comprises mounting and electrically connecting a plurality of components to the substrate.

19. The method of Claim 18 wherein step (c) comprises:

- 1) surface mounting at least one of the components to the substrate; and
- 2) wire bonding at least one of the components to the substrate.